PCN Number:	20180904001		PCN Date:	Septe	ember	05, 2018	
Title: Datasheet for UCC27710, UCC27712							
	PCN Manager				ept: Quality Services		
Change Type:					-	,	
Assembly Site		Design			Wafer	r Bump Site	
Assembly Process			t		Wafer Bump Material		
		Part numb	umber change		r Bump Process		
Mechanical Specification Test		Test Site					
Packing/Shipping/l	Labeling Test Process		SS			Wafer Fab Materials	
					Wafer	r Fab Process	
Notification Details							
Description of Change:							
Texas Instruments Incorporated is announcing an information only notification. The product datasheet(s) is being updated as summarized below. The following change history provides further details.							
TEXAS INSTRUMENTS						UCC27710	
				SLUSD05	B-OCTOE	BER 2017-REVISED AUGUST 2018	
Texas Instruments				SLUS	SCE9A – JU	UCC27712 INE 2017-REVISED AUGUST 2018	
Updated Device Information to match package diagram.							
			Maximum Raung	s table			
The datasheet number	will be changin						
Device Family			Change From:		Change To:		
UCC27710		SLU	SLUSD05A		SLUSD05B		
UCC27712			SLUSCE9 SLUS			CE9A	
These changes may be reviewed at the datasheet links provided.							
http://www.ti.com/product/UCC27710							
http://www.ti.com/product/UCC27712							
Reason for Change:							
To accurately reflect device characteristics.							
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):							
No anticipated impact. This is a specification change announcement only. There are no changes to the actual device.							
Changes to product identification resulting from this PCN:							
None.							
Product Affected:							
UCC27710D	UCC27710D	R	UCC27712D			UCC27712DR	
	-						

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com